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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4/M0
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, IrDA, Microwire, SD, SPI, SSI, SSP, UART/USART, USB, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I ² S, POR, PWM, WDT
Number of I/O	49
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	264K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 4x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFBGA
Supplier Device Package	100-TFBGA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc4330fet100y

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P4_2	D3	A2	-	8	[2]	N; PU	I/O	GPIO2[2] — General purpose digital input/output pin.
							O	CTOUT_0 — SCTimer/PWM output 0. Match output 0 of timer 0.
							O	LCD_VD3 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							O	LCD_VD12 — LCD data.
							I	U3_RXD — Receiver input for USART3.
							I/O	SGPIO8 — General purpose digital input/output pin.
P4_3	C2	B2	-	7	[5]	N; PU	I/O	GPIO2[3] — General purpose digital input/output pin.
							O	CTOUT_3 — SCTimer/PWM output 3. Match output 3 of timer 0.
							O	LCD_VD2 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							O	LCD_VD21 — LCD data.
							I/O	U3_BAUD — Baud pin for USART3.
							I/O	SGPIO9 — General purpose digital input/output pin.
P4_4	B1	A1	-	9	[5]	N; PU	AI	ADC0_0 — DAC output; ADC0 and ADC1, input channel 0. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
							I/O	GPIO2[4] — General purpose digital input/output pin.
							O	CTOUT_2 — SCTimer/PWM output 2. Match output 2 of timer 0.
							O	LCD_VD1 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							O	LCD_VD20 — LCD data.
							I/O	U3_DIR — RS-485/EIA-485 output enable/direction control for USART3.
							I/O	SGPIO10 — General purpose digital input/output pin.
							O	DAC — DAC output. Shared between 10-bit ADC0/1 and DAC.. Configure the pin as GPIO input and use the analog function select register in the SCU to select the DAC.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P4_9	L2	J2	-	33	[2]	N; PU	-	R — Function reserved.
							I	CTIN_6 — SCTimer/PWM input 6. Capture input 1 of timer 3.
							O	LCD_VD11 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[13] — General purpose digital input/output pin.
							O	LCD_VD15 — LCD data.
							I	CAN1_RD — CAN1 receiver input.
							I/O	SGPIO14 — General purpose digital input/output pin.
P4_10	M3	L3	-	35	[2]	N; PU	-	R — Function reserved.
							I	CTIN_2 — SCTimer/PWM input 2. Capture input 2 of timer 0.
							O	LCD_VD10 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[14] — General purpose digital input/output pin.
							O	LCD_VD14 — LCD data.
							-	R — Function reserved.
							I/O	SGPIO15 — General purpose digital input/output pin.
P5_0	N3	L2	-	37	[2]	N; PU	I/O	GPIO2[9] — General purpose digital input/output pin.
							O	MCOB2 — Motor control PWM channel 2, output B.
							I/O	EMC_D12 — External memory data line 12.
							-	R — Function reserved.
							I	U1_DSR — Data Set Ready input for UART 1.
							I	T1_CAP0 — Capture input 0 of timer 1.
							-	R — Function reserved.
							-	R — Function reserved.
P5_1	P3	M1	-	39	[2]	N; PU	I/O	GPIO2[10] — General purpose digital input/output pin.
							I	MCI2 — Motor control PWM channel 2, input.
							I/O	EMC_D13 — External memory data line 13.
							-	R — Function reserved.
							O	U1_DTR — Data Terminal Ready output for UART 1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART 1.
							I	T1_CAP1 — Capture input 1 of timer 1.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P6_5	P16	L14	F9	82	[2]	N; PU	I/O	GPIO3[4] — General purpose digital input/output pin.
							O	CTOUT_6 — SCTimer/PWM output 6. Match output 2 of timer 1.
							I	U0_RXD — Receiver input for USART0.
							O	EMC_RAS — LOW active SDRAM Row Address Strobe.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P6_6	L14	K12	-	83	[2]	N; PU	I/O	GPIO0[5] — General purpose digital input/output pin.
							O	EMC_BLS1 — LOW active Byte Lane select signal 1.
							I/O	SGPIO5 — General purpose digital input/output pin.
							I	USB0_PWR_FAULT — Port power fault signal indicating overcurrent condition; this signal monitors over-current on the USB bus (external circuitry required to detect over-current condition).
							-	R — Function reserved.
							I	T2_CAP3 — Capture input 3 of timer 2.
							-	R — Function reserved.
							-	R — Function reserved.
P6_7	J13	H11	-	85	[2]	N; PU	-	R — Function reserved.
							I/O	EMC_A15 — External memory address line 15.
							I/O	SGPIO6 — General purpose digital input/output pin.
							O	USB0_IND1 — USB0 port indicator LED control output 1.
							I/O	GPIO5[15] — General purpose digital input/output pin.
							O	T2_MAT0 — Match output 0 of timer 2.
							-	R — Function reserved.
							-	R — Function reserved.
P6_8	H13	F12	-	86	[2]	N; PU	-	R — Function reserved.
							I/O	EMC_A14 — External memory address line 14.
							I/O	SGPIO7 — General purpose digital input/output pin.
							O	USB0_IND0 — USB0 port indicator LED control output 0.
							I/O	GPIO5[16] — General purpose digital input/output pin.
							O	T2_MAT1 — Match output 1 of timer 2.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PA_3	H11	E10	-	-	[3]	N; PU	I/O	GPIO4[10] — General purpose digital input/output pin.
							I	QEI_PHA — Quadrature Encoder Interface PHA input.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PA_4	G13	E12	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_9 — SCTimer/PWM output 9. Match output 3 of timer 3.
							-	R — Function reserved.
							I/O	EMC_A23 — External memory address line 23.
							I/O	GPIO5[19] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PB_0	B15	D14	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_10 — SCTimer/PWM output 10. Match output 3 of timer 3.
							O	LCD_VD23 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[20] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PB_1	A14	A13	-	-	[2]	N; PU	-	R — Function reserved.
							I	USB1_ULPI_DIR — ULPI link DIR signal. Controls the ULP data line direction.
							O	LCD_VD22 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[21] — General purpose digital input/output pin.
							O	CTOUT_6 — SCTimer/PWM output 6. Match output 2 of timer 1.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PC_7	G5	-	-	-	[2]	N; PU	-	R — Function reserved.
							I/O	USB1_ULPI_D1 — ULPI link bidirectional data line 1.
							-	R — Function reserved.
							I	ENET_RXD3 — Ethernet receive data 3 (MII interface).
							I/O	GPIO6[6] — General purpose digital input/output pin.
							-	R — Function reserved.
							O	T3_MAT0 — Match output 0 of timer 3.
							I/O	SD_DAT3 — SD/MMC data bus line 3.
PC_8	N4	-	-	-	[2]	N; PU	-	R — Function reserved.
							I/O	USB1_ULPI_D0 — ULPI link bidirectional data line 0.
							-	R — Function reserved.
							I	ENET_RX_DV — Ethernet Receive Data Valid (RMII/MII interface).
							I/O	GPIO6[7] — General purpose digital input/output pin.
							-	R — Function reserved.
							O	T3_MAT1 — Match output 1 of timer 3.
PC_9	K2	-	-	-	[2]	N; PU	I	SD_CD — SD/MMC card detect input.
							-	R — Function reserved.
							I	USB1_ULPI_NXT — ULPI link NXT signal. Data flow control signal from the PHY.
							-	R — Function reserved.
							I	ENET_RX_ER — Ethernet receive error (MII interface).
							I/O	GPIO6[8] — General purpose digital input/output pin.
							-	R — Function reserved.
PC_10	M5	-	-	-	[2]	N; PU	O	T3_MAT2 — Match output 2 of timer 3.
							O	SD_POW — SD/MMC power monitor output.
							-	R — Function reserved.
							O	USB1_ULPI_STP — ULPI link STP signal. Asserted to end or interrupt transfers to the PHY.
							I	U1_DSR — Data Set Ready input for UART 1.
							-	R — Function reserved.
							I/O	GPIO6[9] — General purpose digital input/output pin.
PC_10	M5	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	T3_MAT3 — Match output 3 of timer 3.
							I/O	SD_CMD — SD/MMC command signal.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PE_11	D16	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_12 — SCTimer/PWM output 12. Match output 3 of timer 3.
							O	U1_TXD — Transmitter output for UART 1.
							I/O	EMC_D30 — External memory data line 30.
							I/O	GPIO7[11] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PE_12	D15	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_11 — SCTimer/PWM output 11. Match output 3 of timer 2.
							I	U1_RXD — Receiver input for UART 1.
							I/O	EMC_D31 — External memory data line 31.
							I/O	GPIO7[12] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PE_13	G14	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_14 — SCTimer/PWM output 14. Match output 2 of timer 3.
							I/O	I2C1_SDA — I2C1 data input/output (this pin does not use a specialized I2C pad).
							O	EMC_DQMOUT3 — Data mask 3 used with SDRAM and static devices.
							I/O	GPIO7[13] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PE_14	C15	-	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							O	EMC_DYCS3 — SDRAM chip select 3.
							I/O	GPIO7[14] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.

7.14 One-Time Programmable (OTP) memory

The OTP provides 64 bit + 256 bit One-Time Programmable (OTP) memory for general-purpose use.

7.15 General-Purpose I/O (GPIO)

The LPC4350/30/20/10 provide eight GPIO ports with up to 31 GPIO pins each.

Device pins that are not connected to a specific peripheral function are controlled by the GPIO registers. Pins may be dynamically configured as inputs or outputs. Separate registers allow setting or clearing any number of outputs simultaneously. The value of the output register may be read back as well as the current state of the port pins.

All GPIO pins default to inputs with pull-up resistors enabled and input buffer disabled on reset. The input buffer must be turned on in the system control block SFS register before the GPIO input can be read.

7.15.1 Features

- Accelerated GPIO functions:
 - GPIO registers are located on the AHB so that the fastest possible I/O timing can be achieved.
 - Mask registers allow treating sets of port bits as a group, leaving other bits unchanged.
 - All GPIO registers are byte and half-word addressable.
 - Entire port value can be written in one instruction.
- Bit-level set and clear registers allow a single instruction set or clear of any number of bits in one port.
- Direction control of individual bits.
- Up to eight GPIO pins can be selected from all GPIO pins to create an edge- or level-sensitive GPIO interrupt request (GPIO interrupts).
- Two GPIO group interrupts can be triggered by any pin or pins in each port (GPIO group0 and group1 interrupts).

7.16 Configurable digital peripherals

7.16.1 State Configurable Timer (SCTimer/PWM) subsystem

The SCTimer/PWM allows a wide variety of timing, counting, output modulation, and input capture operations. The inputs and outputs of the SCTimer/PWM are shared with the capture and match inputs/outputs of the 32-bit general-purpose counter/timers.

The SCTimer/PWM can be configured as two 16-bit counters or a unified 32-bit counter. In the two-counter case, in addition to the counter value the following operational elements are independent for each half:

- State variable
- Limit, halt, stop, and start conditions
- Values of Match/Capture registers, plus reload or capture control values

After a few commands configure the interface at startup, the entire flash content is accessible as normal memory using byte, halfword, and word accesses by the processor and/or DMA channels. Simple sequences of commands handle erasing and programming.

Many serial flash devices use a half-duplex command-driven SPI protocol for device setup and initialization and then move to a half-duplex, command-driven 4-bit protocol for normal operation. Different serial flash vendors and devices accept or require different commands and command formats. SPIFI provides sufficient flexibility to be compatible with common flash devices and includes extensions to help insure compatibility with future devices.

7.17.2.1 Features

- Interfaces to serial flash memory in the main memory map.
- Supports classic and 4-bit bidirectional serial protocols.
- Half-duplex protocol compatible with various vendors and devices.
- Quad SPI Flash Interface (SPIFI) with 1-, 2-, or 4-bit data at rates of up to 52 MB per second.
- Supports DMA access.

7.17.3 SD/MMC card interface

The SD/MMC card interface supports the following modes to control:

- Secure Digital memory (SD version 3.0).
- Secure Digital I/O (SDIO version 2.0).
- Consumer Electronics Advanced Transport Architecture (CE-ATA version 1.1).
- MultiMedia Cards (MMC version 4.4).

7.17.4 External Memory Controller (EMC)

The LPC4350/30/20/10 EMC is a Memory Controller peripheral offering support for asynchronous static memory devices such as RAM, ROM, and NOR flash. In addition, it can be used as an interface with off-chip memory-mapped devices and peripherals.

7.17.4.1 Features

- Dynamic memory interface support including single data rate SDRAM.
- Asynchronous static memory device support including RAM, ROM, and NOR flash, with or without asynchronous page mode.
- Low transaction latency.
- Read and write buffers to reduce latency and to improve performance.
- 8/16/32 data and 24 address lines-wide static memory support.
- 16 bit and 32 bit wide chip select SDRAM memory support.
- Static memory features include:
 - Asynchronous page mode read
 - Programmable Wait States
 - Bus turnaround delay

- Supports auto USB 2.0 mode discovery.
- Supports all high-speed USB-compliant peripherals if connected to external ULPI PHY.
- Supports all full-speed USB-compliant peripherals.
- Supports interrupts.
- This module has its own, integrated DMA engine.
- USB interface electrical test software included in ROM USB stack.

7.17.7 LCD controller

Remark: The LCD controller is available on LPC4350 only. See [Table 2](#).

The LCD controller provides all of the necessary control signals to interface directly to various color and monochrome LCD panels. Both STN (single and dual panel) and TFT panels can be operated. The display resolution is selectable and can be up to 1024×768 pixels. Several color modes are provided, up to a 24-bit true-color non-palettized mode. An on-chip 512 byte color palette allows reducing bus utilization (that is, memory size of the displayed data) while still supporting many colors.

The LCD interface includes its own DMA controller to allow it to operate independently of the CPU and other system functions. A built-in FIFO acts as a buffer for display data, providing flexibility for system timing. Hardware cursor support can further reduce the amount of CPU time required to operate the display.

7.17.7.1 Features

- AHB master interface to access frame buffer.
- Setup and control via a separate AHB slave interface.
- Dual 16-deep programmable 64-bit wide FIFOs for buffering incoming display data.
- Supports single and dual-panel monochrome Super Twisted Nematic (STN) displays with 4-bit or 8-bit interfaces.
- Supports single and dual-panel color STN displays.
- Supports Thin Film Transistor (TFT) color displays.
- Programmable display resolution including, but not limited to: 320×200 , 320×240 , 640×200 , 640×240 , 640×480 , 800×600 , and 1024×768 .
- Hardware cursor support for single-panel displays.
- 15 gray-level monochrome, 3375 color STN, and 32 K color palettized TFT support.
- 1, 2, or 4 bits-per-pixel (bpp) palettized displays for monochrome STN.
- 1, 2, 4, or 8 bpp palettized color displays for color STN and TFT.
- 16 bpp true-color non-palettized for color STN and TFT.
- 24 bpp true-color non-palettized for color TFT.
- Programmable timing for different display panels.
- 256 entry, 16-bit palette RAM, arranged as a 128×32 -bit RAM.
- Frame, line, and pixel clock signals.
- AC bias signal for STN, data enable signal for TFT panels.
- Supports little and big-endian, and Windows CE data formats.

transfers, with frames of 4 bit to 16 bit of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

7.18.4.1 Features

- Maximum SSP speed in full-duplex mode of 25 Mbit/s; for transmit only 50 Mbit/s (master) and 17 Mbit/s (slave).
- Compatible with Motorola SPI, 4-wire Texas Instruments SSI, and National Semiconductor Microwire buses.
- Synchronous serial communication.
- Master or slave operation.
- 8-frame FIFOs for both transmit and receive.
- 4-bit to 16-bit frame.
- DMA transfers supported by GPDMA.

7.18.5 I²C-bus interface

Remark: The LPC4350/30/20/10 contain two I²C-bus interfaces.

The I²C-bus is bidirectional for inter-IC control using only two wires: a Serial Clock line (SCL) and a Serial Data line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (for example an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I²C is a multi-master bus and can be controlled by more than one bus master connected to it.

7.18.5.1 Features

- I²C0 is a standard I²C-compliant bus interface with open-drain pins. I²C0 also supports Fast mode plus with bit rates up to 1 Mbit/s.
- I²C1 uses standard I/O pins with bit rates of up to 400 kbit/s (Fast I²C-bus).
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I²C-bus can be used for test and diagnostic purposes.
- All I²C-bus controllers support multiple address recognition and a bus monitor mode.

7.18.6 I²S interface

Remark: The LPC4350/30/20/10 contain two I²S-bus interfaces.

- Selectable time period from $(T_{cy(WDCLK)} \times 256 \times 4)$ to $(T_{cy(WDCLK)} \times 2^{24} \times 4)$ in multiples of $T_{cy(WDCLK)} \times 4$.
- The Watchdog Clock (WDCLK) uses the IRC as the clock source.

7.20 Analog peripherals

7.20.1 Analog-to-Digital Converter (ADC0/1)

7.20.1.1 Features

- 10-bit successive approximation analog to digital converter.
- Input multiplexing among 8 pins.
- Power-down mode.
- Measurement range 0 to VDDA.
- Sampling frequency up to 400 kSamples/s.
- Burst conversion mode for single or multiple inputs.
- Optional conversion on transition on ADCTRIG0 or ADCTRIG1 pins, combined timer outputs 8 or 15, or the PWM output MCOA2.
- Individual result registers for each A/D channel to reduce interrupt overhead.
- DMA support.

7.20.2 Digital-to-Analog Converter (DAC)

7.20.2.1 Features

- 10-bit resolution.
- Monotonic by design (resistor string architecture).
- Controllable conversion speed.
- Low-power consumption.

7.21 Peripherals in the RTC power domain

7.21.1 RTC

The Real-Time Clock (RTC) is a set of counters for measuring time when system power is on, and optionally when it is off. It uses little power when the CPU does not access its registers, especially in the reduced power modes. A separate 32 kHz oscillator clocks the RTC. The oscillator produces a 1 Hz internal time reference and is powered by its own power supply pin, VBAT.

7.21.1.1 Features

- Measures the passage of time to maintain a calendar and clock. Provides seconds, minutes, hours, day of month, month, year, day of week, and day of year.
- Ultra-low power design to support battery powered systems. Uses power from the CPU power supply when it is present.
- Dedicated battery power supply pin.
- RTC power supply is isolated from the rest of the chip.

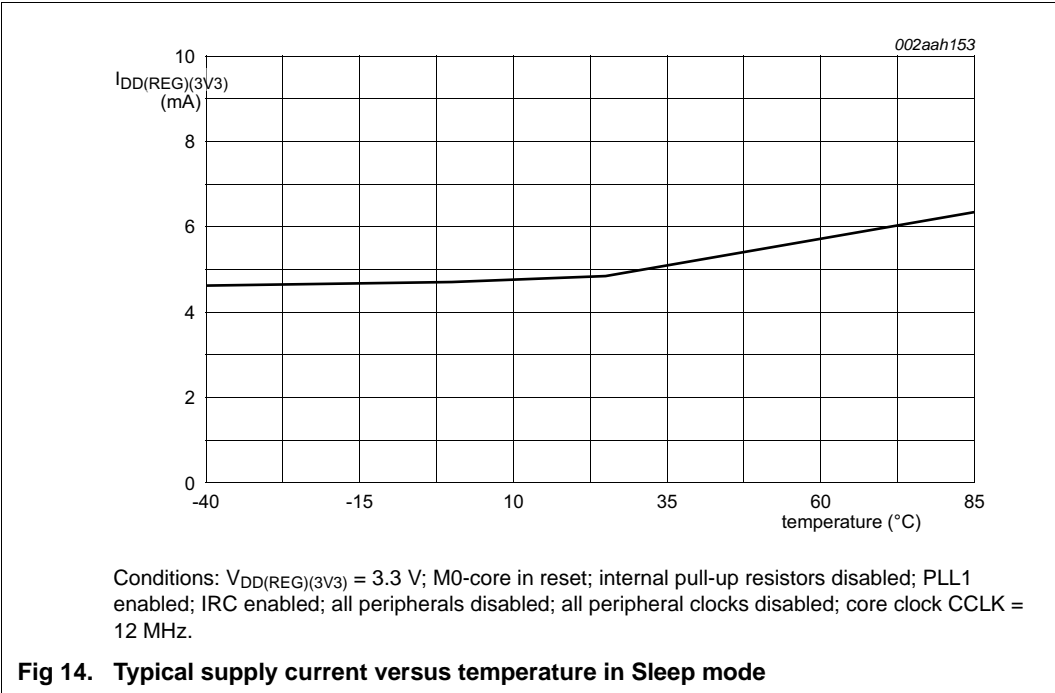
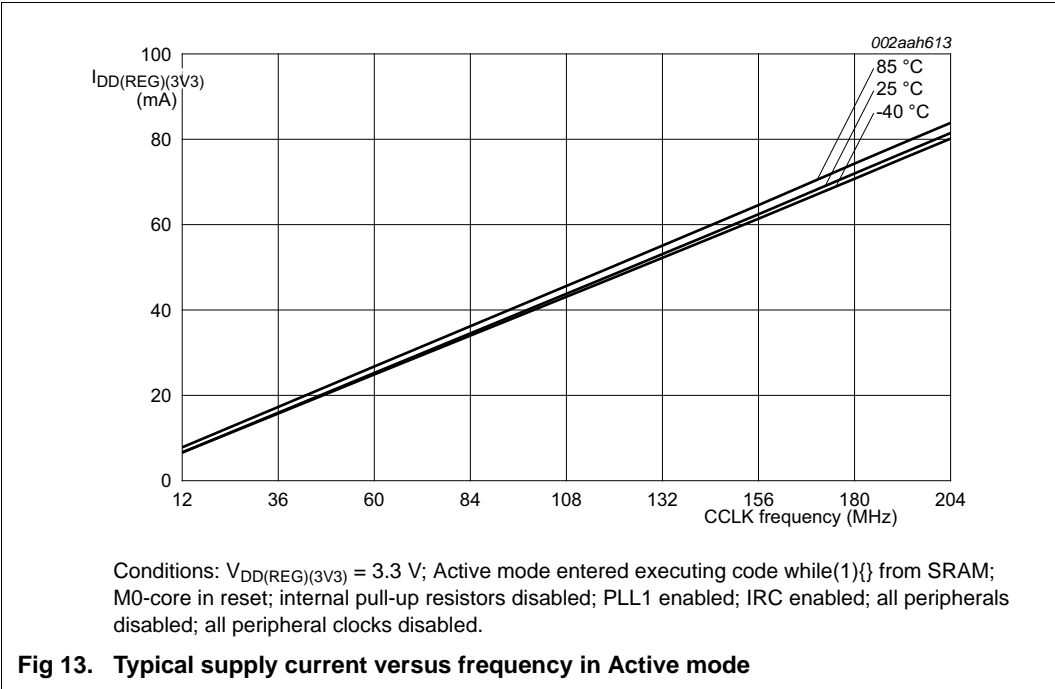


Table 11. Peripheral power consumption

Peripheral	Branch clock	I _{DD(REG)(3V3)} in mA	
		Branch clock frequency = 48 MHz	Branch clock frequency = 96 MHz
LCD	CLK_M4_LCD	0.85	1.72
ETHERNET	CLK_M4_ETHERNET	1.05	2.09
UART0	CLK_M4_UART0, CLK_APB0_UART0	0.3	0.38
UART1	CLK_M4_UART1, CLK_APB0_UART1	0.27	0.48
UART2	CLK_M4_UART2, CLK_APB2_UART2	0.27	0.47
UART3	CLK_M4_USART3, CLK_APB2_UART3	0.29	0.49
TIMER0	CLK_M4_TIMER0	0.07	0.14
TIMER1	CLK_M4_TIMER1	0.07	0.14
TIMER2	CLK_M4_TIMER2	0.07	0.15
TIMER3	CLK_M4_TIMER3	0.06	0.11
SDIO	CLK_M4_SDIO, CLK_SDIO	0.79	1.37
SCTimer/PWM	CLK_M4_SCT	0.52	1.05
SSP0	CLK_M4_SSP0, CLK_APB0_SSP0	0.12	0.21
SSP1	CLK_M4_SSP1, CLK_APB2_SSP1	0.15	0.28
DMA	CLK_M4_DMA	1.88	3.71
WWDT	CLK_M4_WWDT	0.05	0.08
QEI	CLK_M4_QEI	0.33	0.68
USB0	CLK_M4_USB0, CLK_USB0	1.46	3.32
USB1	CLK_M4_USB1, CLK_USB1	2.83	5.03
RITIMER	CLK_M4_RITIMER	0.04	0.08
EMC	CLK_M4 EMC, CLK_M4 EMC_DIV	3.6	6.97
SCU	CLK_M4_SCU	0.09	0.23
CREG	CLK_M4_CREG	0.37	0.72
SGPIO	CLK_PERIPH_SGPIO	0.1	0.17
SPI	CLK_SPI	0.07	0.11

11.6 GPCLKIN

Table 19. Dynamic characteristic: GPCLKIN

$T_{amb} = 25\text{ }^{\circ}\text{C}$; $2.4\text{ V} \leq V_{DD(REG)(3V3)} \leq 3.6\text{ V}$

Symbol	Parameter	Min	Typ	Max	Unit
GP_CLKIN	input frequency	-	-	25	MHz

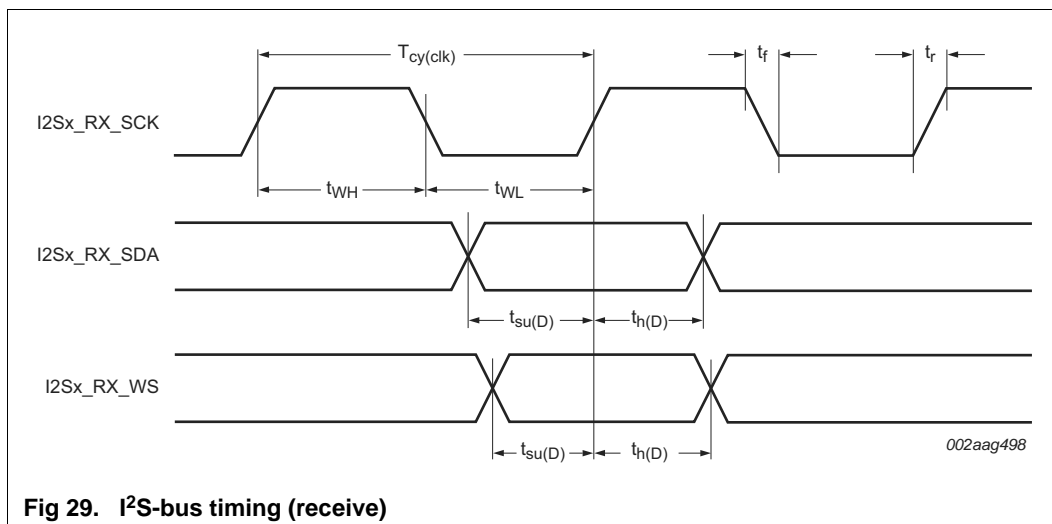
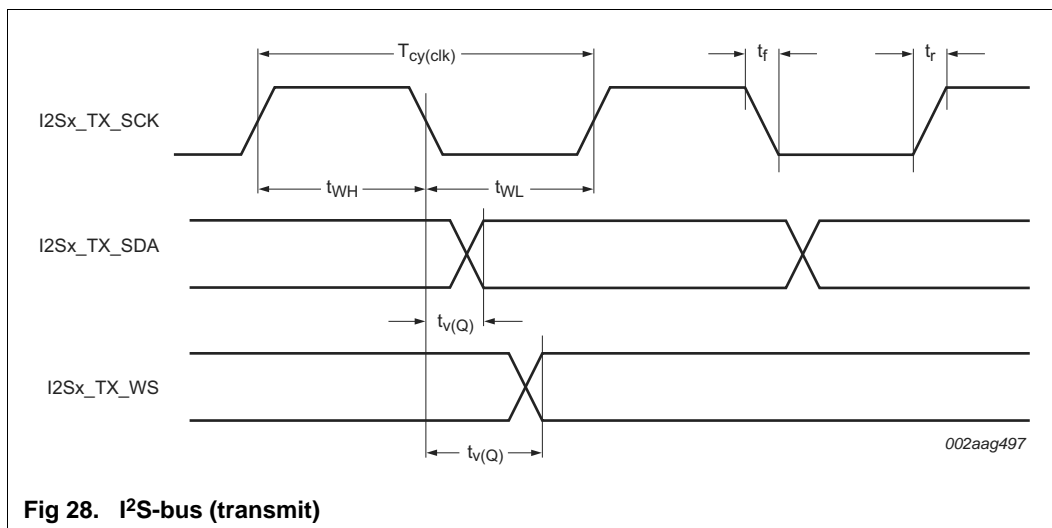
11.7 I/O pins

Table 20. Dynamic characteristic: I/O pins^[1]

$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; $2.7\text{ V} \leq V_{DD(I/O)} \leq 3.6\text{ V}$.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Standard I/O pins - normal drive strength							
t_r	rise time	pin configured as output; EHS = 1	[2][3]	1.0	-	2.5	ns
t_f	fall time	pin configured as output; EHS = 1	[2][3]	0.9	-	2.5	ns
t_r	rise time	pin configured as output; EHS = 0	[2][3]	1.9	-	4.3	ns
t_f	fall time	pin configured as output; EHS = 0	[2][3]	1.9	-	4.0	ns
t_r	rise time	pin configured as input	[4]	0.3	-	1.3	ns
t_f	fall time	pin configured as input	[4]	0.2	-	1.2	ns
I/O pins - high drive strength							
t_r	rise time	pin configured as output; standard drive mode (EHD = 0x0)	[2][5]	4.3	-	7.9	ns
t_f	fall time	pin configured as output; standard drive mode (EHD = 0x0)	[2][5]	4.7	-	8.7	ns
t_r	rise time	pin configured as output; medium drive mode (EHD = 0x1)	[2][5]	3.2	-	5.7	ns
t_f	fall time	pin configured as output; medium drive mode (EHD = 0x1)	[2][5]	3.2	-	5.5	ns
t_r	rise time	pin configured as output; high drive mode (EHD = 0x2)	[2][5]	2.9	-	4.9	ns
t_f	fall time	pin configured as output; high drive mode (EHD = 0x2)	[2][5]	2.5	-	3.9	ns
t_r	rise time	pin configured as output; ultra-high drive mode (EHD = 0x3)	[2][5]	2.8	-	4.7	ns
t_f	fall time	pin configured as output; ultra-high drive mode (EHD = 0x3)	[2][5]	2.4	-	3.4	ns
t_r	rise time	pin configured as input	[4]	0.3	-	1.3	ns
t_f	fall time	pin configured as input	[4]	0.2	-	1.2	ns
I/O pins - high-speed							
t_r	rise time	pin configured as output; EHS = 1	[2][3]	350	-	670	ps
t_f	fall time	pin configured as output; EHS = 1	[2][3]	450	-	730	ps
t_r	rise time	pin configured as output; EHS = 0	[2][3]	1.0	-	1.9	ns
t_f	fall time	pin configured as output; EHS = 0	[2][3]	1.0	-	2.0	ns
t_r	rise time	pin configured as input	[4]	0.3	-	1.3	ns
t_f	fall time	pin configured as input	[4]	0.2	-	1.2	ns

[1] Simulated data.



11.10 USART interface

Table 23. USART dynamic characteristics

$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $85\text{ }^{\circ}\text{C}$; $2.2\text{ V} \leq V_{DD(REG)(3V3)} \leq 3.6\text{ V}$; $2.7\text{ V} \leq V_{DD(10)} \leq 3.6\text{ V}$; $C_L = 20\text{ pF}$. EHS = 1 for all pins. Simulated values.

Symbol	Parameter	Min	Max	Unit
USART master (in synchronous mode)				
$t_{su(D)}$	data input set-up time	26.6	-	ns
$t_{h(D)}$	data input hold time	0	-	ns
$t_{v(Q)}$	data output valid time	0	8.8	ns
USART slave (in synchronous mode)				
$t_{su(D)}$	data input set-up time	1.2	-	ns
$t_{h(D)}$	data input hold time	0.4	-	ns
$t_{v(Q)}$	data output valid time	5.5	24	ns

11.13 SSP/SPI timing diagrams

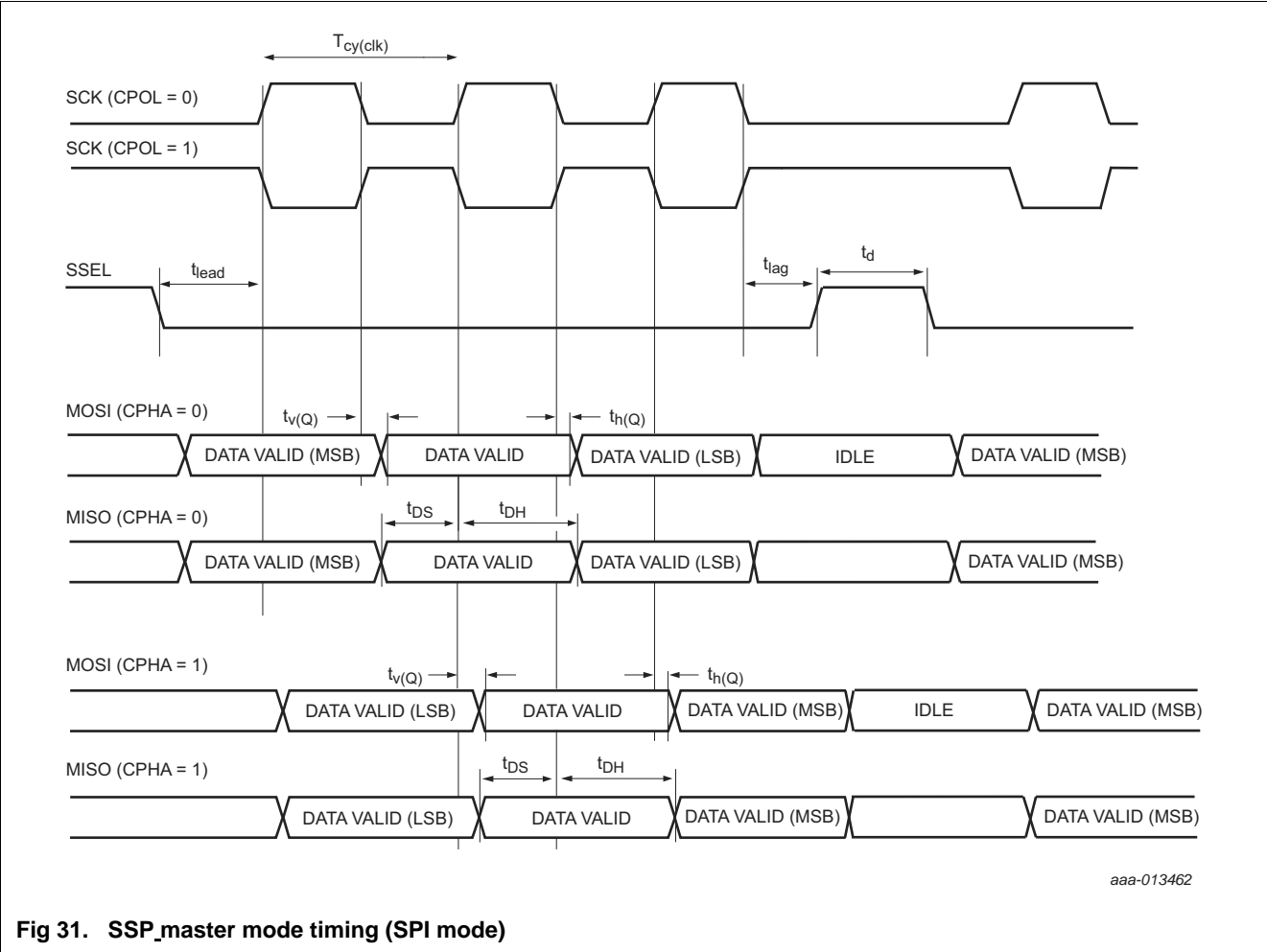
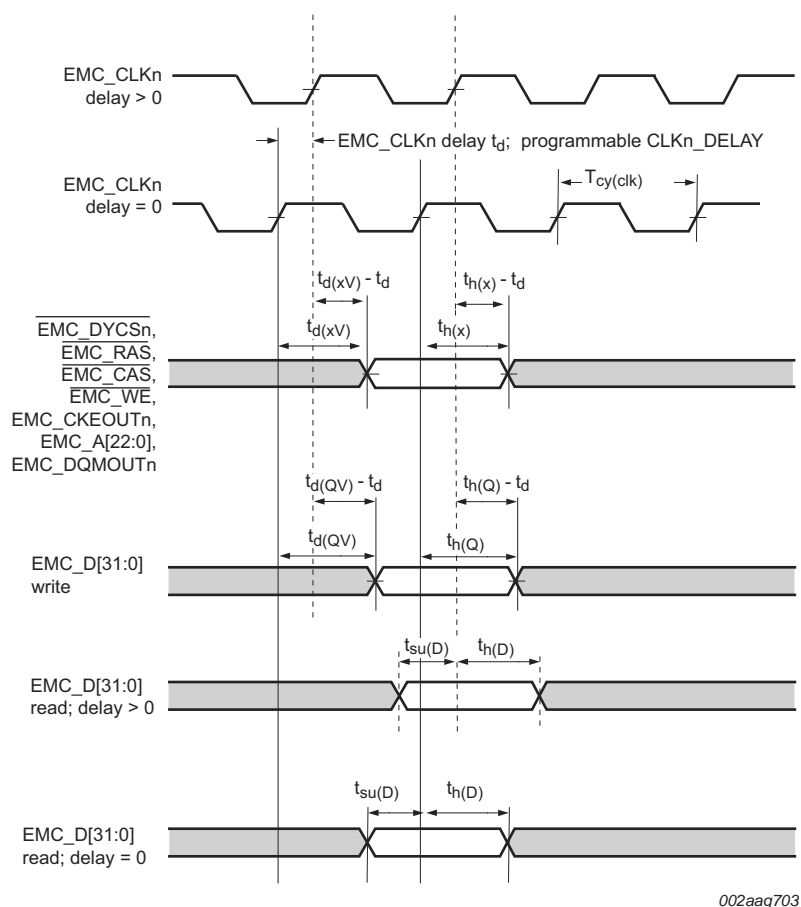


Fig 31. SSP_master mode timing (SPI mode)



For the programmable EMC_CLK[3:0] clock delays $CLKn_DELAY$, see [Table 29](#).

Remark: For SDRAM operation, set $CLK0_DELAY = CLK1_DELAY = CLK2_DELAY = CLK3_DELAY$ in the EMCDELAYCLK register.

Fig 36. SDRAM timing

12. ADC/DAC electrical characteristics

Table 36. ADC characteristics

$V_{DDA(3V3)}$ over specified ranges; $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IA}	analog input voltage			0	-	$V_{DDA(3V3)}$	V
C_{ia}	analog input capacitance			-	-	2	pF
E_D	differential linearity error	$2.7\text{ V} \leq V_{DDA(3V3)} \leq 3.6\text{ V}$	[1][2]	-	± 0.8	-	LSB
		$2.2\text{ V} \leq V_{DDA(3V3)} < 2.7\text{ V}$		-	± 1.0	-	LSB
$E_{L(adj)}$	integral non-linearity	$2.7\text{ V} \leq V_{DDA(3V3)} \leq 3.6\text{ V}$	[3]	-	± 0.8	-	LSB
		$2.2\text{ V} \leq V_{DDA(3V3)} < 2.7\text{ V}$		-	± 1.5	-	LSB
E_O	offset error	$2.7\text{ V} \leq V_{DDA(3V3)} \leq 3.6\text{ V}$	[4]	-	± 0.15	-	LSB
		$2.2\text{ V} \leq V_{DDA(3V3)} < 2.7\text{ V}$		-	± 0.15	-	LSB
E_G	gain error	$2.7\text{ V} \leq V_{DDA(3V3)} \leq 3.6\text{ V}$	[5]	-	± 0.3	-	%
		$2.2\text{ V} \leq V_{DDA(3V3)} < 2.7\text{ V}$		-	± 0.35	-	%
E_T	absolute error	$2.7\text{ V} \leq V_{DDA(3V3)} \leq 3.6\text{ V}$	[6]	-	± 3	-	LSB
		$2.2\text{ V} \leq V_{DDA(3V3)} < 2.7\text{ V}$		-	± 4	-	LSB
R_{vsi}	voltage source interface resistance	see Figure 42		-	-	$1/(7 \times f_{clk(ADC)} \times C_{ia})$	k Ω
R_i	input resistance		[7][8]	-	-	1.2	M Ω
$f_{clk(ADC)}$	ADC clock frequency			-	-	4.5	MHz
f_s	sampling frequency	10-bit resolution; 11 clock cycles		-	-	400	kSamples/s
		2-bit resolution; 3 clock cycles				1.5	MSamples/s

[1] The ADC is monotonic, there are no missing codes.

[2] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 41.

[3] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See Figure 41.

[4] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See Figure 41.

[5] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 41.

[6] The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See Figure 41.

[7] $T_{amb} = 25\text{ }^{\circ}\text{C}$.

[8] Input resistance R_i depends on the sampling frequency f_s : $R_i = 2\text{ k}\Omega + 1 / (f_s \times C_{ia})$.

Table 41. Recommended values for C_{X1/X2} in oscillation mode (crystal and external components parameters) low frequency mode ...continued

Fundamental oscillation frequency	Maximum crystal series resistance R _S	External load capacitors C _{X1} , C _{X2}
12 MHz	< 160 Ω	18 pF, 18 pF
	< 160 Ω	39 pF, 39 pF
16 MHz	< 120 Ω	18 pF, 18 pF
	< 80 Ω	33 pF, 33 pF
20 MHz	<100 Ω	18 pF, 18 pF
	< 80 Ω	33 pF, 33 pF

Table 42. Recommended values for C_{X1/X2} in oscillation mode (crystal and external components parameters) high frequency mode

Fundamental oscillation frequency	Maximum crystal series resistance R _S	External load capacitors C _{X1} , C _{X2}
15 MHz	< 80 Ω	18 pF, 18 pF
20 MHz	< 80 Ω	39 pF, 39 pF
	< 100 Ω	47 pF, 47 pF

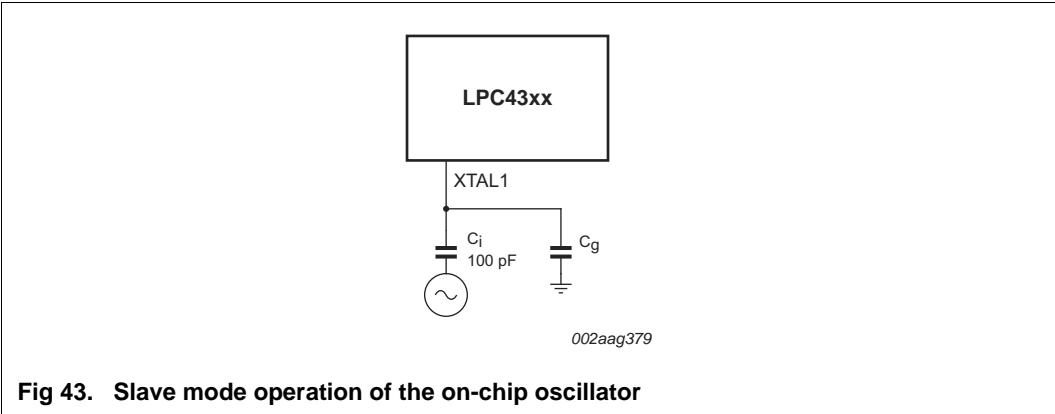


Fig 43. Slave mode operation of the on-chip oscillator

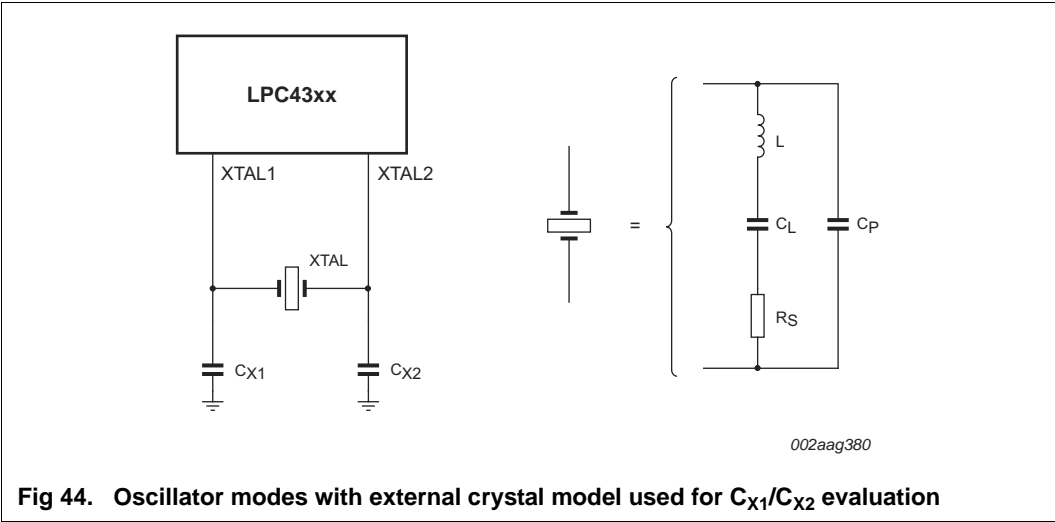


Fig 44. Oscillator modes with external crystal model used for C_{X1}/C_{X2} evaluation

16. Abbreviations

Table 43. Abbreviations

Acronym	Description
ADC	Analog-to-Digital Converter
AHB	Advanced High-performance Bus
APB	Advanced Peripheral Bus
API	Application Programming Interface
BOD	BrownOut Detection
CAN	Controller Area Network
CMAC	Cipher-based Message Authentication Code
CSMA/CD	Carrier Sense Multiple Access with Collision Detection
DAC	Digital-to-Analog Converter
DC-DC	Direct Current-to-Direct Current
DMA	Direct Memory Access
GPIO	General-Purpose Input/Output
IRC	Internal RC
IrDA	Infrared Data Association
JTAG	Joint Test Action Group
LCD	Liquid Crystal Display
LSB	Least Significant Bit
MAC	Media Access Control
MCU	MicroController Unit
MIIM	Media Independent Interface Management
n.c.	not connected
OHCI	Open Host Controller Interface
OTG	On-The-Go
PHY	Physical Layer
PLL	Phase-Locked Loop
PMC	Power Mode Control
PWM	Pulse Width Modulator
RIT	Repetitive Interrupt Timer
RMII	Reduced Media Independent Interface
SDRAM	Synchronous Dynamic Random Access Memory
SIMD	Single Instruction Multiple Data
SPI	Serial Peripheral Interface
SSI	Serial Synchronous Interface
SSP	Synchronous Serial Port
UART	Universal Asynchronous Receiver/Transmitter
ULPI	UTMI+ Low Pin Interface
USART	Universal Synchronous Asynchronous Receiver/Transmitter
USB	Universal Serial Bus
UTMI	USB2.0 Transceiver Macrocell Interface